

HIGH STRENGTH LEAD-FREE SOLDER MATERIALS**ABSTRACT**

Disclosures are lead-free solder alloys having tensile properties exceeding those of near-eutectic 60Sn-40Pb (wt. %) alloys. The alloys are based on the Sn-Cu-Ga, Sn-Cu-Ga-In, Sn-Cu-Ga-In-Zn, Sn-Cu-In, Sn-Ag-In, Sn-Ag-Bi-Se/Te, Sn-Ag-In-Bi-Se/Te, and Sn-Ag-In-Bi-Ga systems.

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